



Ex: NaCl . Ironically Bonded Solid









- Physical bonds, not chemical
 - Bond energy is very weak compared to others
 - Exists between almost all atoms and molecules
 - Arise from atomic or molecular dipoles





Classification of engineering materials



THE STRUCTURE OF CRYSTALLINE SOLIDS





3.3 UNIT CELL

• Unit cell -- smallest grouping which can be arranged in three dimensions to create the lattice. Thus the Unit Cell is basic structural unit or building block of the crystal structure









BODY CENTERED CUBIC STRUCTURE (BCC)OPAOPAOPACr, Fe, W, Nb, Ba, V













Coordination Number

- The number of touching or nearest neighbor atoms
- SC is 6
- BCC is 8
- FCC is 12
- HCP is 12











3.5 Density Computations

- •
- Density of a material can be determined theoretically from the knowledge of its crystal structure (from its Unit cell information)
- Density= mass/Volume
- Mass is the mass of the unit cell and volume is the unit cell volume.
- mass = (number of atoms/unit cell) "n" x mass/atom
- mass/atom = atomic weight "A"/Avogadro's Number "N_A"
- Volume = Volume of the unit cell "V_c"



Example problem on Density Computation Problem: Compute the density of Copper Given: Atomic radius of Cu = 0.128 nm (1.28 x 10⁻⁸ cm) Atomic Weight of Cu = 63.5 g/mol Crystal structure of Cu is FCC Solution: $\rho = n A / V_c N_A$ n=4 $V_c = a^3 = (2R\sqrt{2})^3 = 16 R^3 \sqrt{2}$ $N_A = 6.023 x 10^{23} atoms/mol$

 $\rho = 4 \text{ x } 63.5 \text{ g/mol} / 16 \sqrt{2}(1.28 \text{ x } 10^{-8} \text{ cm})^3 \text{ x } 6.023 \text{ x } 10^{23} \text{ atoms/mol}$

Ans = 8.98 g/cm^3

Experimentally determined value of density of $Cu = 8.94 \text{ g/cm}^3$

3.6 Crystal Systems

- Since there are many different possible crystal structures, it is sometimes convenient to divide them into groups according to unit cell configurations and/or atomic arrangements.
- One such scheme is based on the unit cell geometry, i.e. the shape of the appropriate unit cell parallelepiped without regard to the atomic positions in the cell.
- Within this framework, an x, y, and z coordinate system is established with its origin at one of the unit cell corners; each x, y, and z-axes coincides with one of the three parallelepiped edges that extend from this corner, as illustrated in Figure.





C

- Miller Indices for crystallographic planes are the reciprocals of the fractional intercepts (with fractions cleared) which the plane makes with the crystallographic x,y,z axes of the three nonparallel edges of the cubic unit cell.
- 4-Step Procedure:
- 1. Find the intercepts that the plane makes with the three axes x,y,z. If the plane passes through origin change the origin or draw a parallel plane elsewhere (e.g. in adjacent unit cell)
- 2. Take the reciprocal of the intercepts
- 3. Remove fractions
- 4. Enclose in ()

FIGURE 3.11 (a) Reduced-sphere BCC unit cell with (110) plane. (b) Atomic packing of a BCC (110) plane. Corresponding atom positions from (a) are indicated.

FIGURE 3.12 (a) Reducedsphere FCC unit cell with the [110] direction indicated. (b) The bottom face-plane of the FCC unit cell in (a) on which is shown the atomic spacing in the [110] direction, through atoms labeled X, Y, and Z.

Crystalline and Noncrystalline Materials Single Crystals

- For a crystalline solid, when the periodic and repeated arrangement of atoms is perfect or extends throughout the entirety of the specimen without interruption, the result is a single crystal.
- All unit cells interlock in the same way and have the same orientation.
- Single crystals exist in nature, but may also be produced artificially.
- They are ordinarily difficult to grow, because the environment must be carefully controlled.
- Example: Electronic microcircuits, which employ single crystals of silicon and other semiconductors.

• Defects in Solids

> 0D, Point defects

- ✓ vacancies
- ✓ interstitials
- \checkmark impurities, weight and atomic composition

> 1D, Dislocations

- ✓ edge
- ✓ screw

> 2D, Grain boundaries

Why are defects important?

Defects have a profound impact on the various properties of materials:

Production of advanced semiconductor devices require not only a rather perfect Si crystal as starting material, but also involve introduction of specific defects in small areas of the sample.

Defects are responsible for color (& price) of a diamond crystal.

Forging a metal tool introduces defects ... and increases strength of the tool.

Types of Defects

Defects may be classified into four categories depending on their dimension:

> 0D, Point defects: atoms missing or in irregular places in the lattice (lattice vacancies, substitutional and interstitial impurities, self-interstitials)

> 1D, Linear defects: groups of atoms in irregular positions (e.g. screw and edge dislocations)

> 2D, Planar defects: the interfaces between homogeneous regions of the material (e.g. grain boundaries, stacking faults, external surfaces)

Point Defects: Vacancies

Vacancy = absence of an atom from its normal location in a perfect crystal structure

Vacancies are always present in crystals and they are particularly numerous at high temperatures, when atoms are frequently and randomly change their positions leaving behind empty lattice sites (vacancies).

Other point defects: self-interstitials, impurities

Schematic representation of different point defects:

- vacancy;
- (2) self-interstitial;
- interstitial impurity;
- (4,5) substitutional impurities

The arrows show the local stresses introduced by the point defects.

Due to the local stresses introduced by point defects, they can feel each other (interact) and feel external stresses.

The interactions can give a directionality to otherwise random jumps of atoms.

Self-interstitials:

Self-interstitials in metals introduce large distortions in the surrounding lattice \Rightarrow the energy of self-interstitial formation is ~ 3 times larger as compared to vacancies ($Q_i \sim 3 \times Q_v$) \Rightarrow equilibrium concentration of self-interstitials is very low (less than one self-interstitial per cm³ at room T).

Impurities

Impurities - atoms which are different from the host

- All real solids are impure. Very pure metals 99.9999%
 one impurity per 10⁶ atoms
- May be intentional or unintentional

Examples: carbon added in small amounts to iron makes steel, which is stronger than pure iron. Boron added to silicon change its electrical properties.

Alloys - deliberate mixtures of metals Example: sterling silver is 92.5% silver – 7.5% copper alloy. Stronger than pure silver.

substitutional impurity

interstitial impurities

Dislocations—Linear Defects

Dislocations are linear defects: the interatomic bonds are significantly distorted only in the immediate vicinity of the dislocation line. This area is called the **dislocation core**. Dislocations also create small elastic deformations of the lattice at large distances.

Dislocations are very important in mechanical properties of material (Chapters 6, 7, 8). Introduction/discovery of dislocations in 1934 by Taylor, Orowan and Polyani marked the beginning of our understanding of mechanical properties of materials.

Description of Dislocations—Burgers Vector

To describe the size and the direction of the lattice distortion caused by a dislocation we should introduce socalled **Burgers vector b**. To find the Burgers vector, we should make a circuit from from atom to atom counting the same number of atomic distances in all directions. If the circuit encloses a dislocation it will not close. The vector that closes the loop is the Burgers vector **b**.

Dislocations shown above have Burgers vector directed perpendicular to the dislocation line. These dislocations are called edge dislocations.

Shear occurs by dislocation movement producing permanent (plastic) deformation by "slip"

تمثيل حركة الانخلاعة بحركة (دودة القز).

Edge and screw dislocations

Dislocations shown in previous slide are edge dislocations. They have Burgers vector directed perpendicular to the dislocation line.

There is a second basic type of dislocation, called **screw dislocation**. The screw dislocation is parallel to the direction in which the crystal is being displaced (Burgers vector is parallel to the dislocation line).

Where do dislocations come from ?

The number of dislocations in a material is expressed as the **dislocation density** - the total dislocation length per unit volume or the number of dislocations intersecting a unit area. Dislocation densities can vary from 10^5 cm⁻² in carefully solidified metal crystals to 10^{12} cm⁻² in heavily deformed metals.

Most crystalline materials, especially metals, have dislocations in their as-formed state, mainly as a result of stresses (mechanical, thermal...) associated with the forming process.

The number of dislocations increases dramatically during plastic deformation (Ch.7). Dislocations spawn from existing dislocations, grain boundaries & surfaces

This picture is a snapshot from simulation of plastic deformation in a fcc single crystal (Cu) of linear dimension 15 micrometers.

Atomistic simulation of crack propagation

Planar (interfacial) defects

External Surfaces

Surface atoms have have unsatisfied atomic bonds, and higher energies than the bulk atoms \Rightarrow Surface energy, γ (J/m^2)

· Minimization of surface areas reduces the energy of the system (e.g. liquid drop)

 Solid surfaces can "reconstruct" to satisfy atomic bonds at surfaces.

Grain Boundaries

Polycrystalline material comprised of many small crystals or grains. The grains have different crystallographic orientation. There exist atomic mismatch within the regions where grains meet. These regions are called grain boundaries.

Grain Boundary